Special Issue

Advanced Manufacturing Technologies and Their Applications

Message from the Guest Editor

The manufacturing industry is currently experiencing a worldwide transformation from traditional manufacturing to advanced manufacturing under the 4th Industrial revolution (Industry 4.0), which features Internet-of-Things (IoT) technologies, Big Data Analytics, Cloud Computing, Cyber Security, System Integration, Smart Robotics, Augmented Reality, and Additive Manufacturing and Simulations. This Special Issue is aiming to become a collection of high-quality articles contributed by both practitioners and researchers in the relevant fields of research on advanced manufacturing, from theory to applications. Topics of interest for publication include but are not limited to:

- Additive manufacturing (3D printing) of metals, polymers, ceramics and composites
- Fabrication and evaluation of novel engineering materials
- Advanced sensing technologies for process monitoring and real-time control
- Artificial intelligence, machine learning, and intelligent production systems
- Augmented and virtual reality for manufacturing
- Internet of things (IoT) and big data for manufacturing
- Smart robotics, control, and automation

Guest Editor

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Deadline for manuscript submissions

closed (15 April 2021)

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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